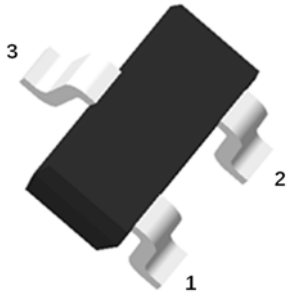
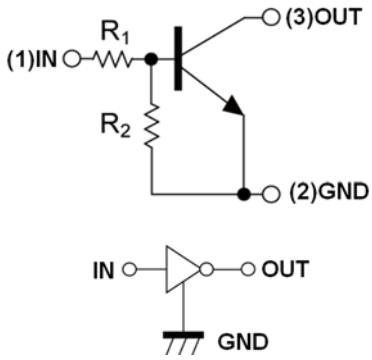
NPN Digital Transistors (Built-in Resistors)





Features

- Moisture sensitivity level 1
- Halogen free and RoHS compliant
- Surface mount package ideally suited for auto matic insertion

Application

- Signal amplification
- Switching circuit

Mechanical data

- **Package**: SOT-523
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102

■ **Maximum Ratings** (T_a=25℃ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Value
Device marking code				E21
Supply voltage	V_{CC}	V		50
Input voltage	V_{IN}	V		-5 to +10
Output current	I_O	mA		100
Power dissipation	P_D	mW		150
Junction temperature	T_J	℃		-55 to +150
Storage temperature	T_{STG}	℃		-55 to +150

■ Electrical Characteristics (Ta=25℃ Unless otherwise specified)

Item	Symbol	Unit	Conditions	Min	Typ	Max
Input voltage	$VI_{(off)}$	V	V_{CC}=5V,Io=100uA	0.3		
	$VI_{(on)}$	V	V_0=0.3V,Io=20mA			3
Output voltage	$Vo_{(on)}$	V	Io=10mA,I_I=0.5mA			0.3
Input current	I_I	mA	V_I=5V			7.2
Output current	$I_{O(off)}$	uA	V_{CC}=50V, V_I=0			0.5
DC current gain	G_I		Vo=5V, Io=5mA	33		
Input resistance	R_1	kΩ		0.7	1	1.3
Resistance ratio	R_2/R_1			8	10	12
Transition frequency	f_T	MHz	Vo=10V,I_O=5mA		250	

■ Thermal Characteristics

Parameter	Symbol	Unit	Value
Thermal resistance, junction-to-ambient	$R_{\theta J-A}$(1)	℃/W	833
Thermal resistance, junction-to-case	$R_{\theta J-C}$(1)	℃/W	666

Note:

（1）Thermal resistance from junction to ambient and from junction to case mounted on P.C.B. with 25.4mm*25.4mm copper pad areas

■ Ordering Information

Preferred P/N	Packing code	Unit weight(g)	Minimum package(pcs)	Inner box quantity(pcs)	Outer carton quantity(pcs)	Delivery mode
DTC113ZE	F2	Approximate 0.0027	3000	30000	120000	7” reel

■ Characteristics

Fig 1：Input Voltage (On) Characteristics

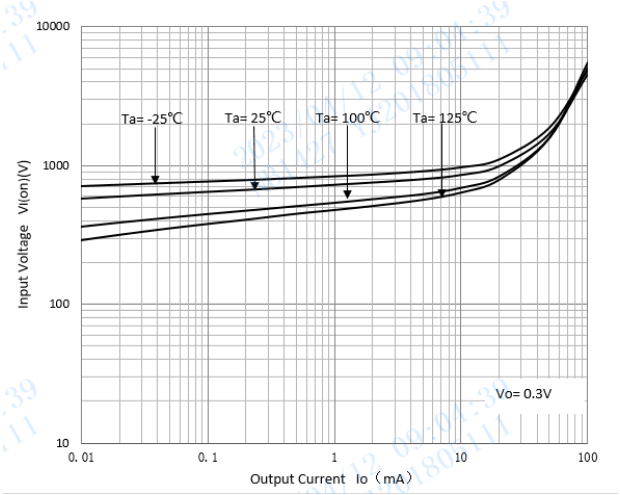


Fig 2：Input Voltage (Off) Characteristics

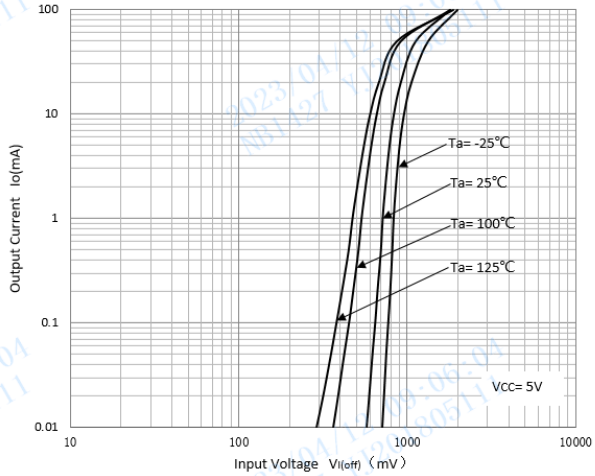


Fig 3：Output Voltage Characteristics

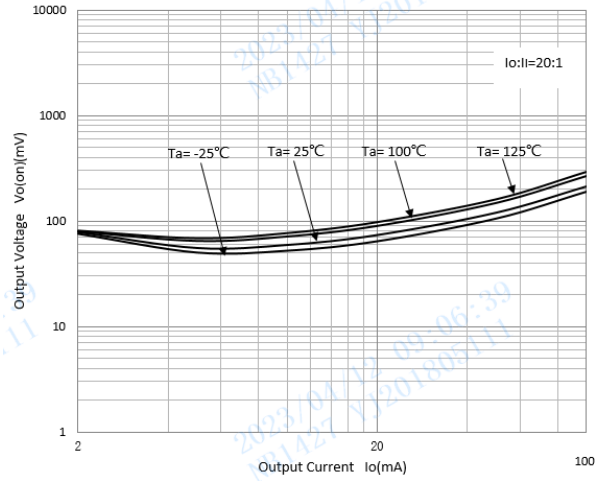


Fig 4：DC Current Gain Characteristics

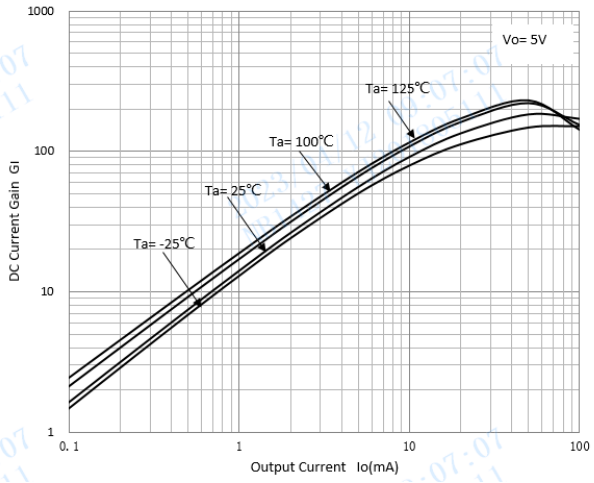
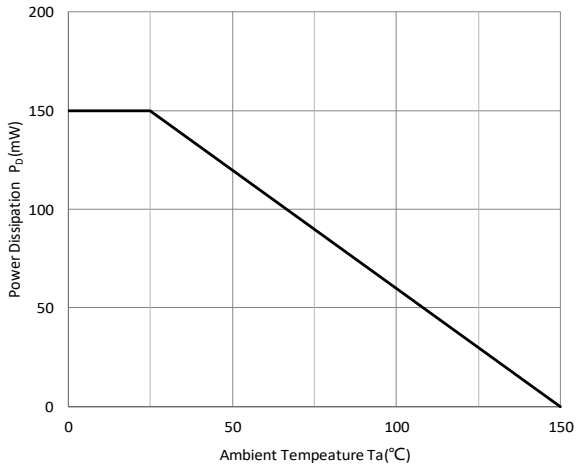
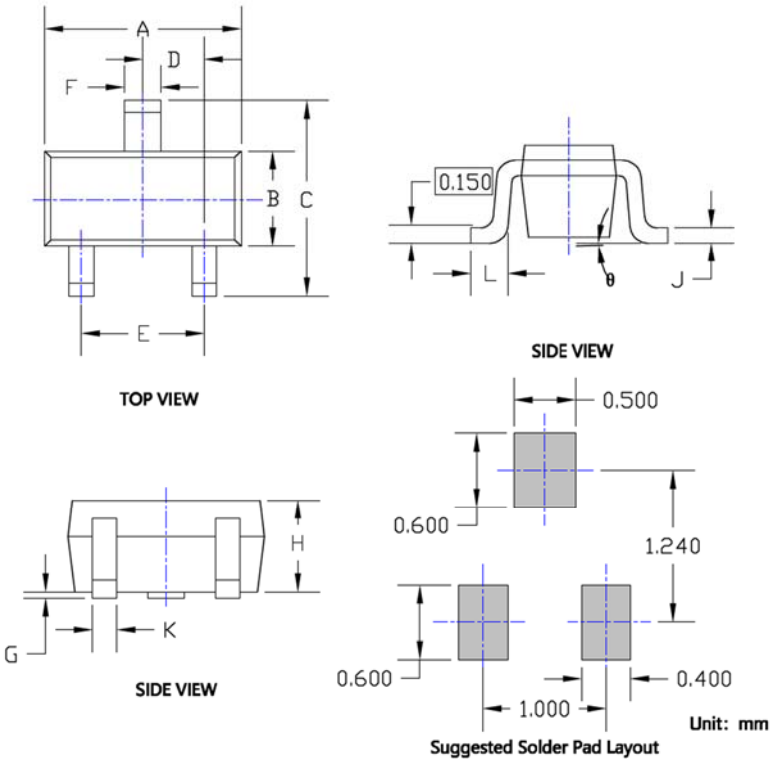


Fig 5：P_D-Ta Curve



■ Outline Dimensions



DIMENSIONS				
SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.059	0.067	1.500	1.700
B	0.030	0.033	0.750	0.850
C	0.057	0.069	1.450	1.750
D	0.020TYP		0.500TYP	
E	0.035	0.043	0.900	1.100
F	0.010	0.018	0.250	0.450
G	0.000	0.004	0.000	0.100
H	0.024	0.031	0.600	0.800
J	0.004	0.008	0.100	0.200
K	0.006	0.014	0.150	0.350
L	0.010	0.018	0.260	0.460
θ	0°	8°	0°	8°

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

Note:
1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
2. General tolerances: ±0.10mm unless otherwise specified.
[通用公差为±0.10mm，除非另有说明]
3. Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
4.All dimensions shown are exclusive of burrs and gate residues. Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
5.Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
6.Dimensions A and B are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[A和B是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
7.Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]
8. ★It is the key size.
[★ 标记为关键尺寸]

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